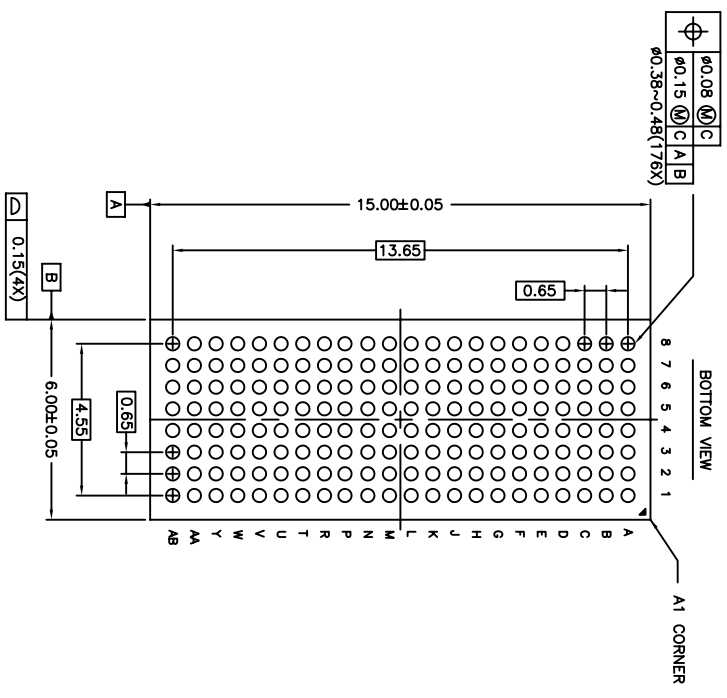
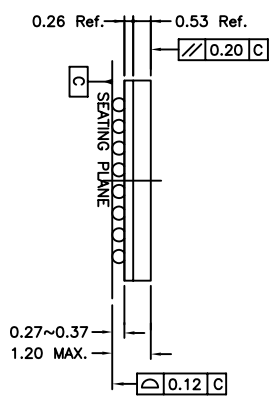
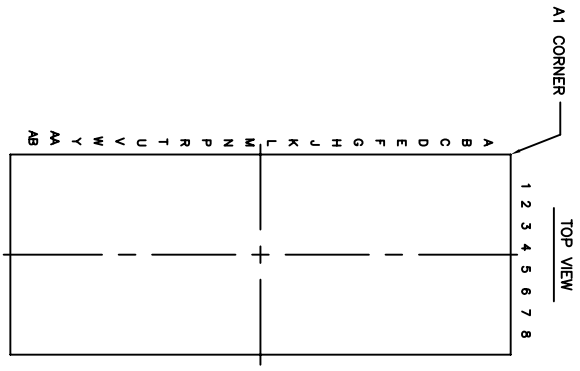



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
02	ADD "GREEN" BKG NOMENCLATURE	10/19/04	TU VU
03	COMBINE POD & LAND PATTERN	06/21/13	KS



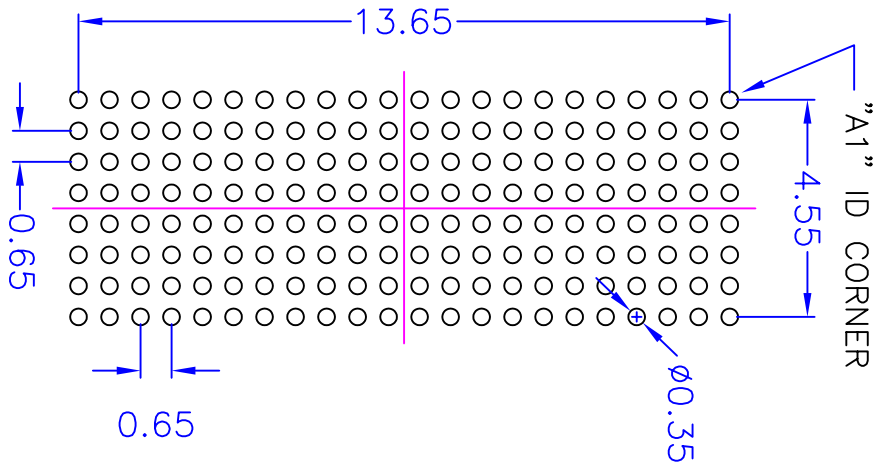
Bell Pitch :	0.65	Substrate Thickness :	0.26
Bell Diameter :	0.40	Mold Thickness :	0.53

TOLERANCES UNLESS SPECIFIED	
DECIMAL	ANGULAR
XX.X	XX.X
XXXX	XXXX
APPROVALS	DATE
DRAWN PXP	02/17/04
CHECKED	
SIZE	DRAWING NO.
C	PSC-4128
REV	03
DO NOT SCALE DRAWING	
SHEET 1 OF 2	


**6024 SILVER CREEK**  
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TITLE BK/BKG 176 PACKAGE OUTLINE  
 6 x 15 mm BODY CTBGA  
 0.65 mm PITCH


REVISIONS			
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RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		APPROVALS	
DECIMAL	ANGULAR	DATE	
XX±		02/17/04	
XXX±			
XXXX			
 6024 SILVER CREEK VALLEY ROAD SAN JOSE CA, 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591 WWW.IDT.COM		TITLE BK/BKG 176 PACKAGE OUTLINE 6 x 15 mm BODY CTBGA 0.65 mm PITCH	
DRAWN	DATE	SIZE	DRAWING No.
02/17/04		C	PSC-4128
CHECKED			
DO NOT SCALE DRAWING			REV 03
			SHEET 2 OF 2